



Docket No. p6202

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:  
**Dabral, et al.**

Examiner: **Norris, Jeremy C.**

Application No.: **09/474,345**

Art Unit: **2827**

Filed: **29 December 1999**

For: **An Inline and Y Input-Output Bus  
Topology**

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage in an envelope addressed to the Assistant Commissioner of Patents, Washington, D.C. 20231

on **November 15, 2002**

Date of Deposit

**Carrie Boccaccini**

Name of Person Mailing Correspondence

*Carrie Boccaccini*  
Signature

**11-15-2002**

Date

Assistant Commissioner for Patents  
Washington, D.C. 20231

**RESPONSE C**

**Request for Reconsideration under CFR §1.111**

Assistant Commissioner for Patents:

In response to the Office Action dated 19 June 2002, Applicants respectfully request reconsideration of the above-identified patent application.

**Remarks**

Claims 1, 2, 5 are presently active, claims 15 and 16 having been withdrawn by constructive election.

In the office action mailed 19 June 2002 ("Office Action"), claims 1, 2, and 5 were rejected under 35 U.S.C. §102(b) as being anticipated by Gold, et al., U.S. patent 3, 568, 129 ("Gold").

Applicants respectfully traverse the rejection. Vias do not correspond to the screws 18 in Gold. Vias are holes that allow for an electrical connection between two conductors, where the two conductors are at different heights (or layers) in a substrate.

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The screws 18 in Gold are merely for securing a plate 20 of insulating material to the base 10. See top of column 2 in Gold. Thus, Plate 20 is taught to be an insulator. Also, note in column 1, line 65, that base 10 is also an insulating material. Consequently, the screws taught by Gold cannot be identified as vias.

Respectfully submitted,

Seth Z. Kalson Dated: 11-15-02

Seth Z. Kalson

Reg. no. 40,670

Attorney for Applicants and Intel Corporation (Assignee)